

AMENDMENTS TO THE SPECIFICATION:

Please insert the following new section on page 1, before the heading "Background of the Invention".

CROSS-REFERENCE TO RELATED APPLICATION

[0001.1] This application is a divisional of application serial no. 10/112,968, filed March 28, 2002, which application is incorporated herein in its entirety by this reference.

Please amend paragraph 0021 as follows:

[0021] FIG. 2b shows vias 128 that have been made through PCB 110 and PCB 112 to connect components on the top and bottom sides of the package 100. Bond wires 124 connect controller die 120 to vias 128. After the bond wires have been formed controller die 120 is encapsulated with encapsulent 132. Encapsulent 132 ~~and 136~~ can be any substance well known in the art such as bakelite, phenolic, epoxy or a thermal setting compound.